

L Number	Hits	Search Text	DB	Time stamp
-	114936	"three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional"	USPAT; US-PGPUB	2002/04/17 16:27
-	923	("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and ((bond or bonding) SAME "thin film")	USPAT; US-PGPUB	2002/04/17 16:33
-	274	((("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and ((bond or bonding) SAME "thin film"))) and (UV or irradiating or irradiate)	USPAT; US-PGPUB	2002/04/17 16:33
-	157	((("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional") and ((bond or bonding) SAME "thin film"))) and (UV or irradiating or irradiate)) and semiconductor	USPAT; US-PGPUB	2002/04/17 16:31
-	3417	transfer with substrate with device	USPAT; US-PGPUB	2002/04/17 16:32
-	4068	(transfer or transferring) with substrate with device	USPAT; US-PGPUB	2002/04/17 16:32
-	331	((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional")	USPAT; US-PGPUB	2002/04/17 16:32
-	121	((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional"))) and "thin film"	USPAT; US-PGPUB	2002/04/17 17:00
-	55	((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional"))) and "thin film") and (UV or irradiating or irradiate)	USPAT; US-PGPUB	2002/04/17 16:33
-	66	((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional"))) and "thin film") NOT (((((transfer or transferring) with substrate with device) and ("three dimensional" or "3 dimensional" or "3-D" or "3 D" or "three-dimensional" or "3-dimensional"))) and "thin film") and (UV or irradiating or irradiate))	USPAT; US-PGPUB	2002/04/17 17:08
-	28	"thin film device" SAME transfer SAME substrate	USPAT; US-PGPUB	2002/04/17 18:02
-	1605	"thin film" SAME transfer SAME substrate	USPAT; US-PGPUB	2002/04/17 18:03
-	835	("thin film" SAME transfer SAME substrate) and (bonding or bonded or bond)	USPAT; US-PGPUB	2002/04/17 18:03
-	502	((("thin film" SAME transfer SAME substrate) and (bonding or bonded or bond)) and semiconductor	USPAT; US-PGPUB	2002/04/17 18:06
-	3	("5821138" "6127199" "6143582").PN.	USPAT	2002/04/17 18:14